U.are.U® 5300 Module
FIPS 201 PIV, FAP 30 Certified USB Fingerprint Module

APPLICATIONS

ID Verification for:

- Civil ID/Voting/Entitlement
- Micro Finance and Healthcare
- Mobile ID terminals

FEATURES

- FIPS 201 PIV certified
- Mobile ID FAP 30 certified
- Low power consumption
- Fine-grained power control
- Compact size
- Blue platen illumination
- 500dpi images
- High-durability glass top surface
- IP64-rated top surface sealed against dust and liquid
- High quality fingerprint image
- Counterfeit finger rejection
- Compatible with U.are.U SDKs

PRODUCT DESCRIPTION

The U.are.U 5300 Fingerprint Module is certified for both FIPS 201/PIV and FBI Mobile ID FAP 30 standards. It produces 500 dot-per-inch (dpi) fingerprint images in ANSI and ISO/IEC standard formats. The hard glass imaging window is sealed against dust and liquids (IP64) and is highly resistant to chemical and physical damage. On-board electronics automatically control calibration and data transfer over the USB interface. Its compact size and convenient mounting features simplify OEM integration.

This self-contained module optically scans the fingerprint when the user touches the glass imaging window. The U.are.U 5300 Module can be used with any standards-compatible fingerprint templates extractor or matcher, including the FingerJet™ Minex-certified Biometric Engine.

The U.are.U 5300 Fingerprint Module is designed for use with a full range of Crossmatch™ U.are.U Software Development Kits. Easy to program and integrate, the U.are.U SDK runtime environment is free to distribute with customer applications. Whether you are an OEM or system integrator, Crossmatch's biometric identity verification solutions provide a natural extension to your applications.
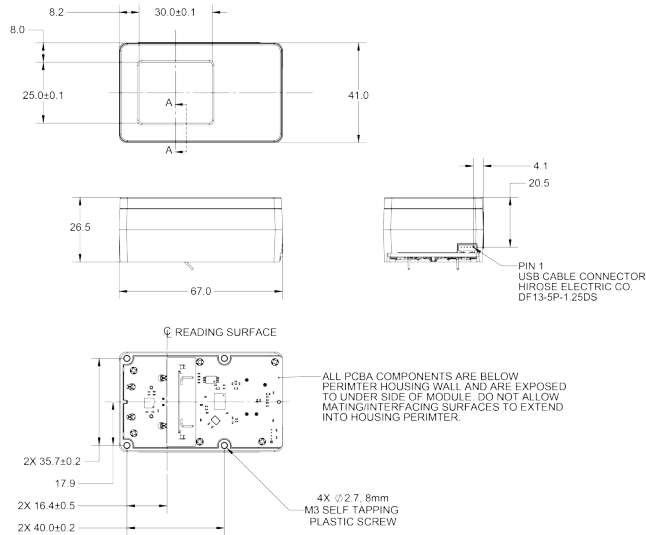
ABOUT CROSSMATCH

Crossmatch helps organizations solve their identity management challenges through biometrics. Our enrollment and authentication solutions are trusted to create, validate and manage identities for a wide range of government, law enforcement, financial institution, retail and commercial applications. Our solutions are designed using proven biometric technologies, flexible enrollment and strong multi-factor authentication software, and deep industry expertise. We offer an experienced professional services capability to assess, design, implement and optimize our identity management solutions for a customer's individual challenges. Our products and solutions are utilized by over 200 million people in more than 80 countries.

Learn more at www.crossmatch.com

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CROSSMATCH™

8.2
8.0
30.0±0.1
25.0±0.1
41.0
A
A

26.5
67.0
4.1
20.5

PIN 1
USB CABLE CONNECTOR
HIROSE ELECTRIC CO.
DF13-5P-1.25DS

READING SURFACE

ALL PCBA COMPONENTS ARE BELOW
PERIMTER HOUSING WALL AND ARE EXPOSED
TO UNDER SIDE OF MODULE. DO NOT ALLOW
MATING/INTERFACING SURFACES TO EXTEND
INTO HOUSING PERIMTER.

2X 35.7±0.2
17.9
2X 16.4±0.5
2X 40.0±0.2

4X ⌀2.7, 8mm
M3 SELF TAPPING
PLASTIC SCREW

KEY SPECIFICATIONS

- Pixel resolution: 500dpi (native), 1000dpi (interpolated)
- 8-bit grayscale (256 gray levels)
- Scan capture area: 20.32 mm x 25.4 mm
- Module size (approximate): 67 mm (l) x 41 mm (w) x 27 mm (h)
- USB 2.0 (High Speed)

RATINGS

Supply Voltage	5.0V ±5%
Supply Current—scanning	< 150 mA (Typical)
Supply Current—idle mode	< 40 mA (Typical)
Supply Current—suspend mode	< 0.5 mA (Maximum)
Temperature, Operating	-10 - 50 C
Humidity, Operating	0% - 90% non-condensing
Temperature, Storage	-20 - 55 C
Humidity, Storage	0% - 90% non-condensing
Scan Data	8-bit grayscale
Top Surface	IP64-rated seal between top case and glass surface*
Interface	USB 2.0 High Speed
Weight	60 grams
Standards Compliance	FIPS 201 PIV, Mobile ID FAP 30, RoHS, REACH, FCC, UL, USB, WEEE Class B, CE, ICES, BSMI, MIC, BSI, WHQL
ESD	EN61000-4-2 ±4kv Contact Discharge ±8kv Air Discharge

CONNECTOR POINTS

USB

Pin 1: +5V

Pin 2: Ground

Pin 3: Shield

Pin 4: D-

Pin 5: D+

Data subject to change without notice

*IP64 rating is for the seal between the top case and the glass imaging window. Devices containing the embedded module must seal the module top case to their chassis or housing to extend the IP64 protection to the device.

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